

SMT Pin Headers

Features and Benefits

- Co-planarity problems are eliminated.
- Minimal real estate is required on the Board.
- They have 50% higher pin retention force.
- Optional configurations are available.
- They allow more forgiving board placement tolerances.
- A visual indicator assures quality processing.
- They are resistant to thermal shock and thermal cycling due to similarity of materials.



Produkt Discription

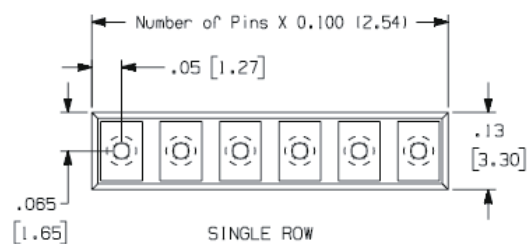
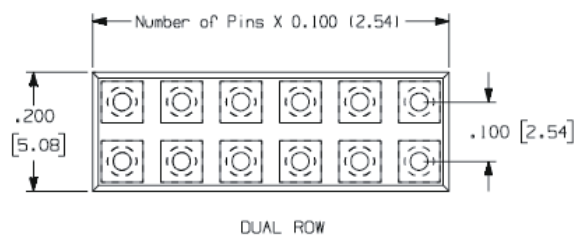
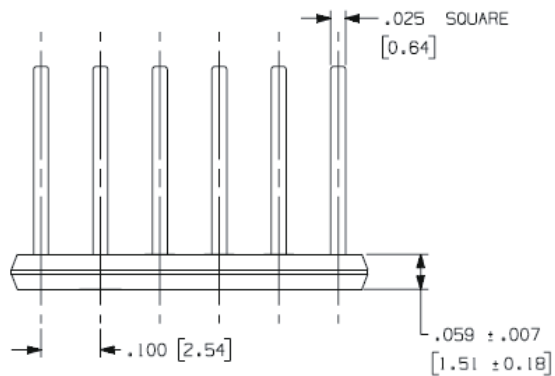
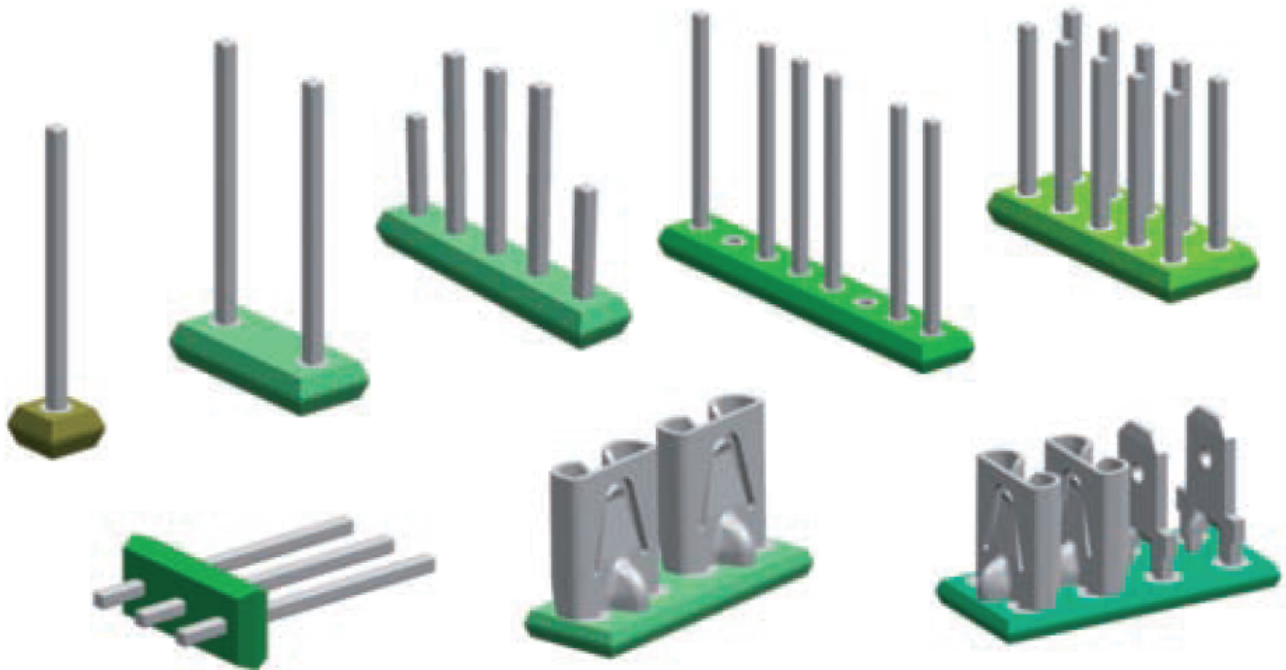
The unique header assembly features capillary action to improve solder joint strength and to reduce the component footprint on the PCB. As a result, pin retention forces are 50% higher than that of J-Lead type headers.

As the capillary action draws the solder, it pulls the header assembly tightly to the PCB. At the same time, coplanarity problems are eliminated because the force generated by the capillary action also pulls the header into proper position over the solder pad, even if the part has been placed off-center.

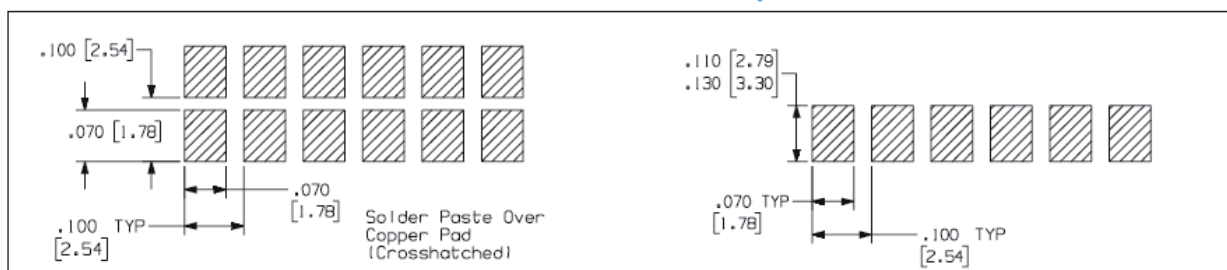
A circular solder pad on top of the board and a square solder pad on the bottom are connected to the conductive wall of the platelet through-hole. The size of the

hole is such that it holds the square pin in place, yet leaves four cavities defined by the flat sides of the pin and the curved wall of the hole. These cavities promote capillary action by drawing most of the melted solder up through the cavities where it forms a ring at the top side of the header assembly board. This solder ring is a visual indication that the reflow process is perfect and complete.

Further, because the header base is made of the same material as the PCB, there are no thermally induced stresses on the solder joint. Long-term reliability is assured. In addition, deep score lines run across both sides of the header base. The assembly is very flexible and can accommodate board warpage without weakening connections.



Recommended Solder Pad Geometry



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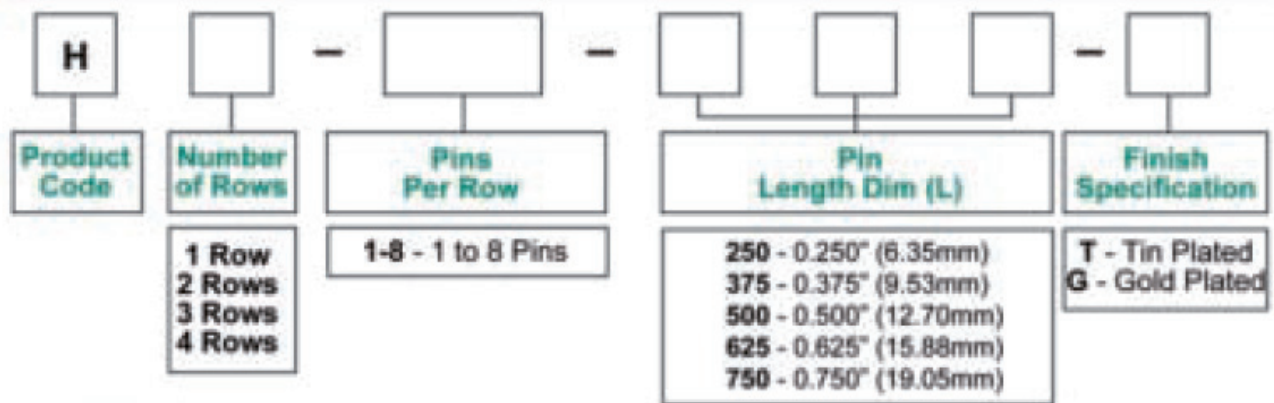
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PART NUMBERING SYSTEM



EXAMPLE

H **1** **08** **250** **G**

H - Product Code, 1 - Single Row Header, 08 - Eight Pins Per Row
250 - 0.250" (6.35mm) Pin Length, G - Gold Plated

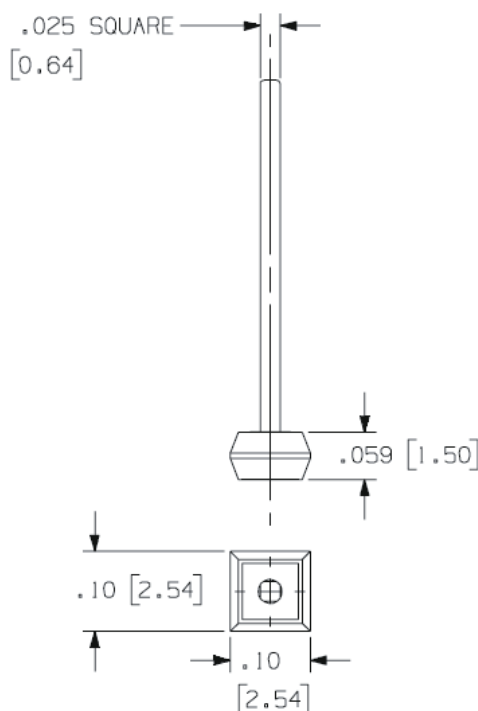
Packaging - Loose Piece or Strip Format

For complete listing of headers available see our website www.zierick.com

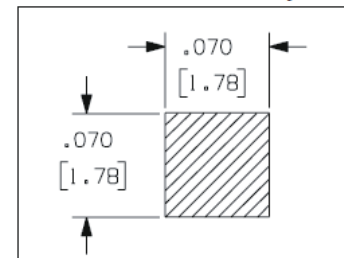
For exact finish specifications and available special finishes, see Finish Table

U.S. Patent Nos. 6,402,531 B1 and 5,816,668

See available Part Numbers at www.zierick.com



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SMT One Pin Headers

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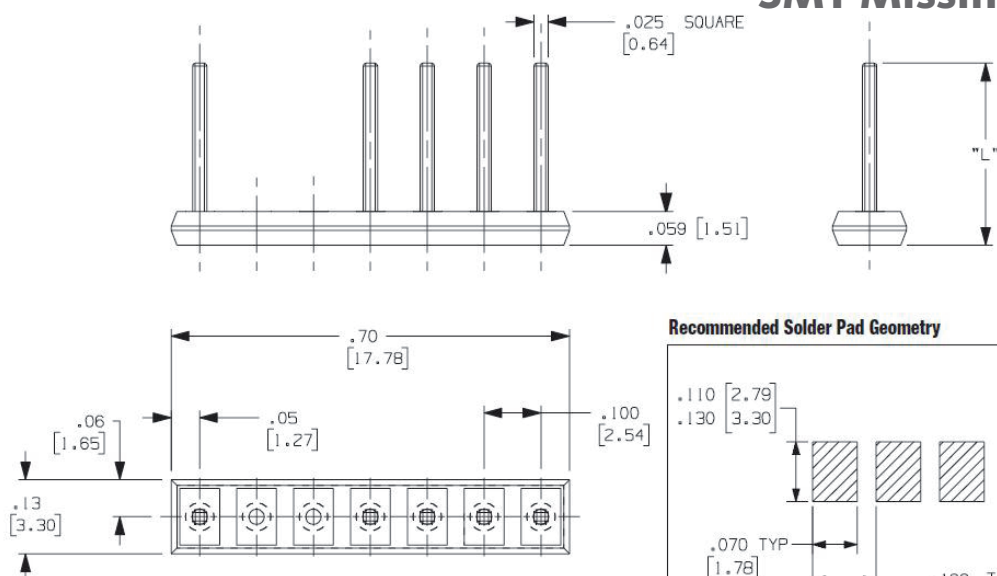
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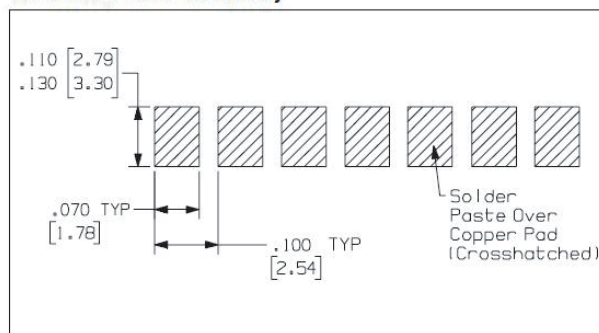
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SMT Missing Pin Headers

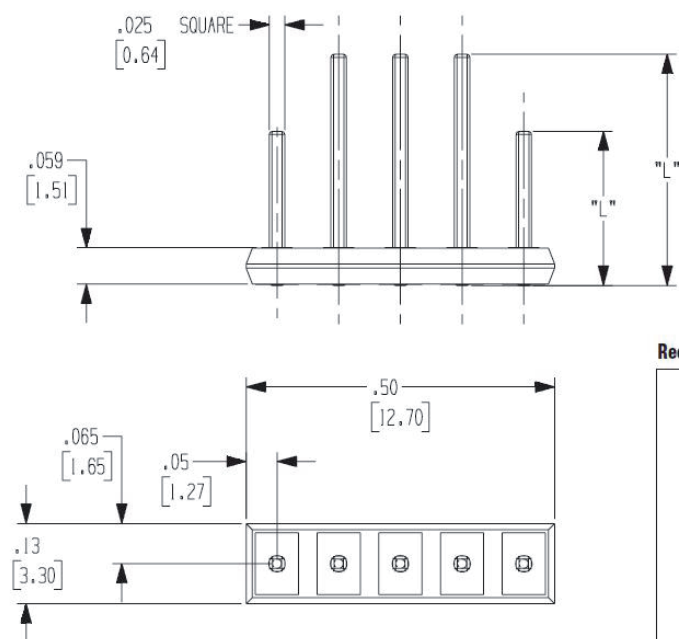


Recommended Solder Pad Geometry

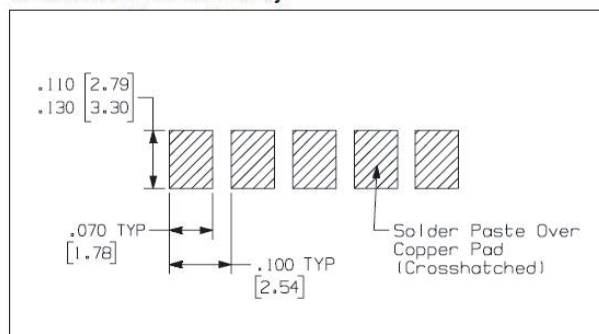


See available Part Numbers at www.zierick.com

SMT Variable Length Headers



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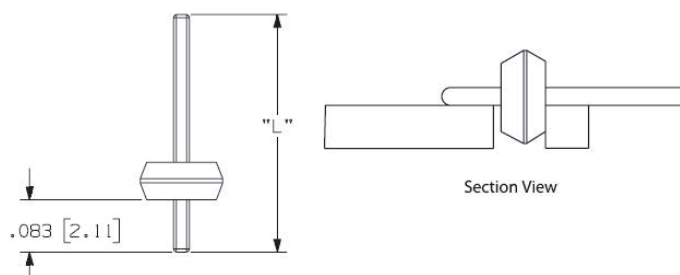
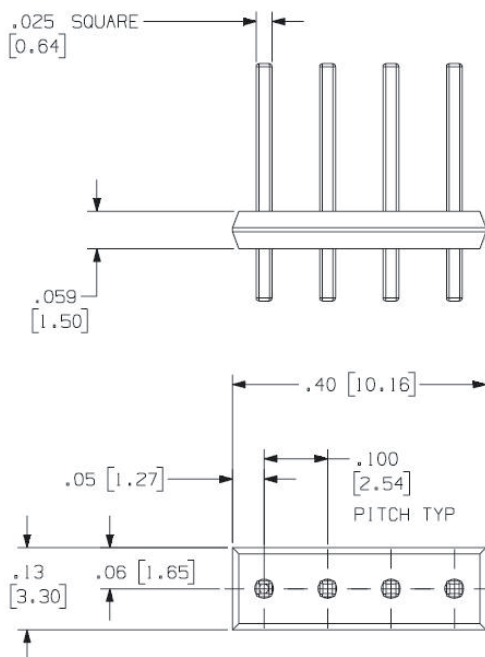
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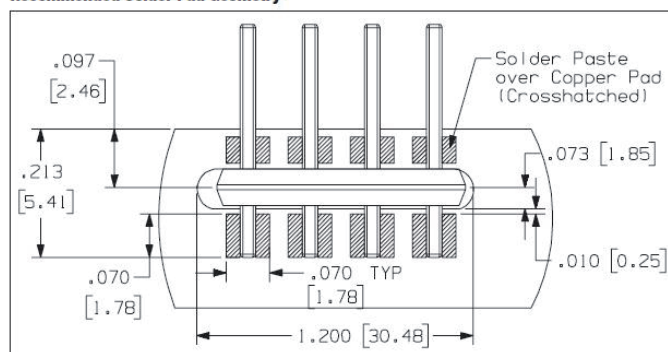
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SMT Horizontal Pin Headers

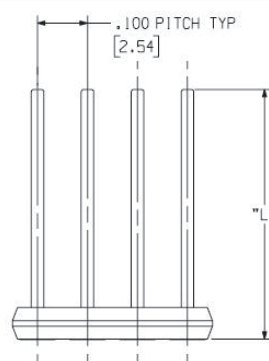
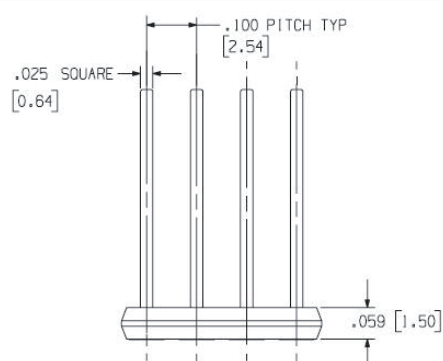


Recommended Solder Pad Geometry

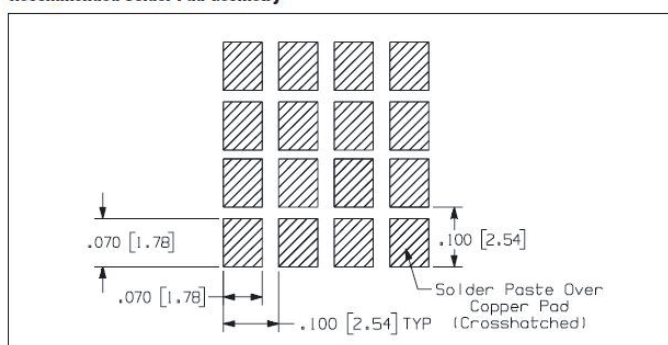


See available Part Numbers at www.zierick.com

SMT Matrix Pin Headers



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